

RoHS Compliant

2GB DDR2 SDRAM SO-DIMM

Product Specifications

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Version 1.1



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General Description

Apacer **78.A2G72.405** is a 256M x 64 Double Data Rate SDRAM high density memory modules based on first generation of 1GB DDR2 SDRAM respectively.

It consists of 16 pieces 128M x 8 bit with 8banks Double Data Rate SDRAMs in 60Ball FBGA packages mounted on a 200pin glass-epoxy substrate. Decoupling capacitors are mounted on the printed circuit board in parallel for each DDR2 SDRAM.

Synchronous design allows precise cycle control with the use of system clock. Data I/O transactions are possible on both edges of DQS. Range of operating frequencies, programmable latencies and burst lengths allow the same device to be useful for a variety of high bandwidth, high performance memory system applications.

Ordering Information

| Part Number | Bandwidth | Speed Grade | Max Frequency | CAS Latency |
|--------------|------------|-------------|---------------|-------------|
| 78.A2G72.405 | 5.3 GB/sec | 667 Mbps | 333 MHz | CL5 |

| Density | Organization | Component | Rank |
|---------|--------------|------------|------|
| 2GB | 256M x 64 | 128M x8*16 | 2 |

Key Parameters

| MT/s | DDR2-667 | DDR2-800 | DDR2-800 | Unit |
|-------------|----------|----------|----------|------|
| Grade | -CL5 | -CL5 | -CL6 | |
| tCK (min) | 3 | 2.5 | 2.5 | ns |
| CAS latency | 5 | 5 | 6 | tCK |
| tRCD (min) | 15 | 12.5 | 15 | ns |
| tRP (min) | 15 | 12.5 | 15 | ns |
| tRAS (min) | 45 | 45 | 45 | ns |
| tRC (min) | 60 | 57.5 | 60 | ns |
| CL-tRCD-tRP | 5-5-5 | 5-5-5 | 6-6-6 | tCK |

Specifications:

- ◆ JEDEC standard 1.8V ± 0.1V
- ◆ Power Supply VDDQ = 1.8V± 0.1V
- ◆ Interface: SSTL_18
- ◆ Posted CAS
- ◆ Programmable CAS Latency: 3, 4, 5
- ◆ Programmable Additive Latency: 0, 1 , 2 , 3 and 4
- ◆ Write Latency(WL) = Read Latency(RL) -1
- ◆ Burst Length: 4 , 8(Interleave/nibble sequential)
- ◆ Programmable Sequential / Interleave Burst Mode
- ◆ On Die Termination
- ◆ Refresh and Self Refresh
- ◆ Average Refresh Period 7.8us
- ◆ Serial presence detect with EEPROM
- ◆ Compliance with RoHS
- ◆ Compliance with CE
- ◆ Supports auto-refresh/self-refresh
- ◆ Operating Temperature Range:
Commercial $0^{\circ}\text{C} \leq \text{TC} \leq 85^{\circ}\text{C}$
- ◆ Average refresh period
7.8us at $0^{\circ}\text{C} \leq \text{TC} \leq 85^{\circ}\text{C}$
3.9us at $85^{\circ}\text{C} \leq \text{TC} \leq 95^{\circ}\text{C}$

Pin Assignments

| Pin No. | Pin name | Pin No. | Pin name | Pin No. | Pin name | Pin No. | Pin name |
|---------|--------------------------|---------|----------|---------|--------------------------|---------|--------------------------|
| 1 | VREF | 51 | DQS2 | 101 | A1 | 151 | DQ42 |
| 3 | VSS | 53 | VSS | 103 | VDD | 153 | DQ43 |
| 5 | DQ0 | 55 | DQ18 | 105 | A10 | 155 | VSS |
| 7 | DQ1 | 57 | DQ19 | 107 | BA0 | 157 | DQ48 |
| 9 | VSS | 59 | VSS | 109 | $\overline{\text{WE}}$ | 159 | DQ49 |
| 11 | $\overline{\text{DQS0}}$ | 61 | DQ24 | 111 | VDD | 161 | VSS |
| 13 | DQS0 | 63 | DQ25 | 113 | CAS# | 163 | NC |
| 15 | VSS | 65 | VSS | 115 | S1# | 165 | VSS |
| 17 | DQ2 | 67 | DM3 | 117 | VDD | 167 | $\overline{\text{DQS6}}$ |
| 19 | DQ3 | 69 | NC | 119 | ODT1 | 169 | DQS6 |
| 21 | VSS | 71 | VSS | 121 | VSS | 171 | VSS |
| 23 | DQ8 | 73 | DQ26 | 123 | DQ32 | 173 | DQ50 |
| 25 | DQ9 | 75 | DQ27 | 125 | DQ33 | 175 | DQ51 |
| 27 | VSS | 77 | VSS | 127 | VSS | 177 | VSS |
| 29 | $\overline{\text{DQS1}}$ | 79 | CKE0 | 129 | $\overline{\text{DQS4}}$ | 179 | DQ56 |
| 31 | DQS1 | 81 | VDD | 131 | DQS4 | 181 | DQ57 |
| 33 | VSS | 83 | NC | 133 | VSS | 183 | VSS |
| 35 | DQ10 | 85 | NC/BA2 | 135 | DQ34 | 185 | DM7 |
| 37 | DQ11 | 87 | VDD | 137 | DQ35 | 187 | VSS |
| 39 | VSS | 89 | A12 | 139 | VSS | 189 | DQ58 |
| 41 | VSS | 91 | A9 | 141 | DQ40 | 191 | DQ59 |
| 43 | DQ16 | 93 | A8 | 143 | DQ41 | 193 | VSS |
| 45 | DQ17 | 95 | VDD | 145 | VSS | 195 | SDA |
| 47 | VSS | 97 | A5 | 147 | DM5 | 197 | SCL |
| 49 | $\overline{\text{DQS2}}$ | 99 | A3 | 149 | VSS | 199 | VDDSPD |

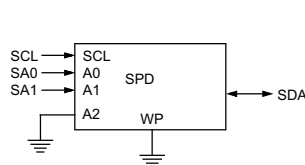
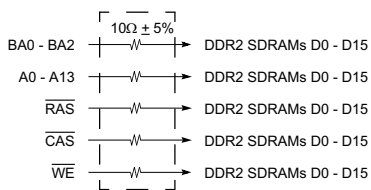
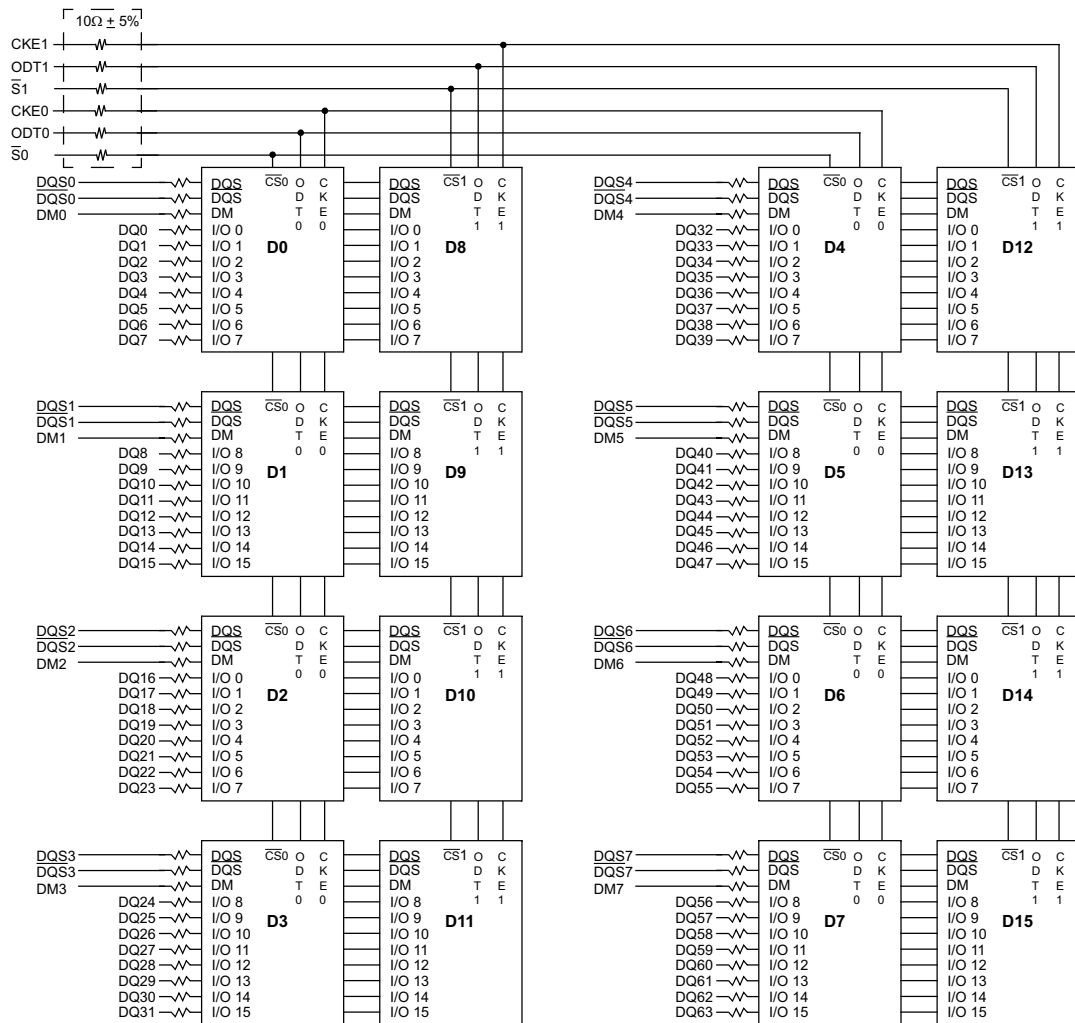
| Pin No. | Pin name | Pin No. | Pin name | Pin No. | Pin name | Pin No. | Pin name |
|---------|-------------------------|---------|--------------------------|---------|--------------------------|---------|--------------------------|
| 2 | VSS | 52 | DM2 | 102 | A0 | 152 | DQ46 |
| 4 | DQ4 | 54 | VSS | 104 | VDD | 154 | DQ47 |
| 6 | DQ5 | 56 | DQ22 | 106 | BA1 | 156 | VSS |
| 8 | VSS | 58 | DQ23 | 108 | $\overline{\text{RAS}}$ | 158 | DQ52 |
| 10 | DM0 | 60 | VSS | 110 | $\overline{\text{S0}}$ | 160 | DQ53 |
| 12 | VSS | 62 | DQ28 | 112 | VDD | 162 | VSS |
| 14 | DQ6 | 64 | DQ29 | 114 | ODT0 | 164 | CK1 |
| 16 | DQ7 | 66 | VSS | 116 | NC | 166 | $\overline{\text{CK1}}$ |
| 18 | VSS | 68 | $\overline{\text{DQS3}}$ | 118 | VDD | 168 | VSS |
| 20 | DQ12 | 70 | DQS3 | 120 | NC | 170 | DM6 |
| 22 | DQ13 | 72 | VSS | 122 | VSS | 172 | VSS |
| 24 | VSS | 74 | DQ30 | 124 | DQ36 | 174 | DQ54 |
| 26 | DM1 | 76 | DQ31 | 126 | DQ37 | 176 | DQ55 |
| 28 | VSS | 78 | VSS | 128 | VSS | 178 | VSS |
| 30 | CK0 | 80 | NC/CKE1 | 130 | DM4 | 180 | DQ60 |
| 32 | $\overline{\text{CK0}}$ | 82 | VDD | 132 | VSS | 182 | DQ61 |
| 34 | VSS | 84 | NC | 134 | DQ38 | 184 | VSS |
| 36 | DQ14 | 86 | NC | 136 | DQ39 | 186 | $\overline{\text{DQS7}}$ |
| 38 | DQ15 | 88 | VDD | 138 | VSS | 188 | DQS7 |
| 40 | VSS | 90 | A11 | 140 | DQ44 | 190 | VSS |
| 42 | VSS | 92 | A7 | 142 | DQ45 | 192 | DQ62 |
| 44 | DQ20 | 94 | A6 | 144 | VSS | 194 | DQ63 |
| 46 | DQ21 | 96 | VDD | 146 | $\overline{\text{DQS5}}$ | 196 | VSS |
| 48 | VSS | 98 | A4 | 148 | DQS5 | 198 | SA0 |
| 50 | NC | 100 | A2 | 150 | VSS | 200 | SA1 |

*Pin 85 is NC for 512MB and BA2 for 1GB

Pin Descriptions

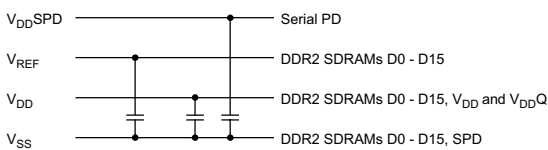
| Pin Name | Description |
|--------------------------|--|
| Ax | SDRAM address bus |
| BAx | SDRAM bank select |
| $\overline{\text{RAS}}$ | SDRAM row address strobe |
| $\overline{\text{CAS}}$ | SDRAM column address strobe |
| $\overline{\text{WE}}$ | SDRAM write enable |
| $\overline{\text{Sx}}$ | DIMM Rank Select Lines |
| CKEx | SDRAM clock enable lines |
| ODTx | On-die termination control lines |
| DQx | DIMM memory data bus |
| DQSx | SDRAM data strobes(positive line of differential pair) |
| $\overline{\text{DQSx}}$ | SDRAM data strobes(negative line of differential pair) |
| DMx | SDRAM data masks high data strobes(x8-based X72 DIMMs) |
| CKx | SDRAM clocks(positive line of differential pair) |
| $\overline{\text{CKx}}$ | SDRAM clocks(negative line of differential pair) |
| SCL | I2C serial bus clock for EEPROM |
| SDA | I2C serial bus data line for EEPROM |
| SAX | I2C slave address select for EEPROM |
| VDD | SDRAM core power supply |
| VDDQ | SDRAM I/O Driver power supply |
| VREF | SDRAM I/O reference supply |
| VSS | Power supply return(ground) |
| VDDSPD | Serial EEPROM positive power supply |
| NC | Spare pins(no connect) |

Functional Block Diagram



| * Clock Wiring | |
|----------------|---------------|
| Clock Input | DDR2 SDRAMs |
| *CK0/CK0 | 8 DDR2 SDRAMs |
| *CK1/CK1 | 8 DDR2 SDRAMs |

* Wire per Clock Loading Table/Wiring Diagrams



- Notes :**
1. DQ,DM, DQS/DQS resistors : 22 Ohms \pm 5%.
 2. BAx, Ax, RAS, CAS, WE resistors : 3.0 Ohms \pm 5%.

Absolute Maximum Ratings

| Parameter | Symbol | Description | Units |
|-------------------------------------|-------------------|-----------------|-------|
| Voltage on VDD pin relative to Vss | V_{DD} | - 0.5 V ~ 2.3 V | V |
| Voltage on VDDQ pin relative to Vss | V_{DDQ} | - 0.5 V ~ 2.3 V | V |
| Voltage on any pin relative to Vss | V_{IN}, V_{OUT} | - 0.5 V ~ 2.3 V | V |
| Storage Temperature | TSTG | -55 to +100 | °C |

Notes:

1. Stress greater than those listed may cause permanent damage to the device. This is a stress rating only and device functional operation at or above the conditions indicated is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DRAM Component Operating Temperature Range

| Symbol | Parameter | Rating | Units | Notes |
|--------|------------------------------------|----------|-------|-------|
| TOPER | Normal Operating Temperature Range | 0 to 85 | °C | 1,2 |
| | Extended Temperature Range | 85 to 95 | °C | 1,3 |

Notes:

1. Operating Temperature TOPER is the case surface temperature on the center / top side of the DRAM. For measurement conditions please refer to the JEDEC document JESD51-2.
2. The Normal Temperature Range specifies the temperatures where all DRAM specifications will be supported during operation, the DRAM case temperature must be maintained between 0°C - 85°C under all operating conditions.
3. Some applications require operation of the DRAM in the Extended Temperature Range between 85°C and 95°C case temperature. Full specifications are guaranteed in this range, but the following additional conditions apply:
 - a. Refresh commands must be doubled in frequency, therefore reducing the Refresh interval tREFI to 3.9 μs.
 - b. If Self-Refresh operation is required in the Extended Temperature Range, then it is mandatory to either use the Manual Self-Refresh mode with Extended Temperature Range capability (MR2 A6 = 0b and MR2 A7 = 1b), in this case IDD6 current can be increased around 10~20% than normal Temperature range.

Operating Conditions

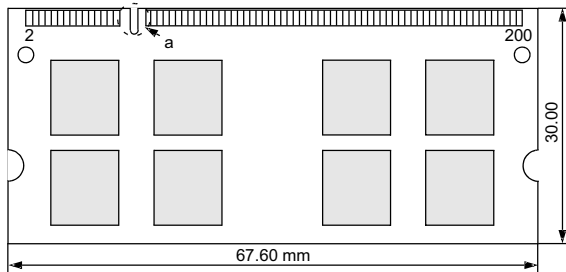
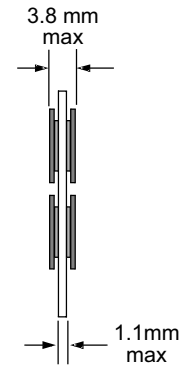
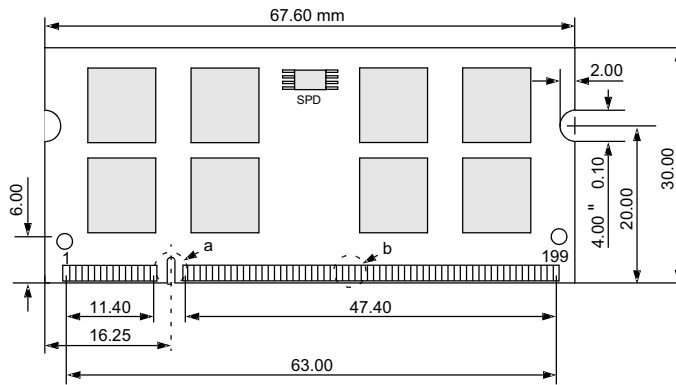
Recommended DC Operating Conditions – DDR2 (1.8V) operation

| Symbol | Parameter | Rating | | | Units |
|--------|---------------------------|--------|------|------|-------|
| | | Min. | Typ. | Max. | |
| VDD | Supply Voltage | 1.7 | 1.8 | 1.9 | V |
| VDDQ | Supply Voltage for Output | 1.7 | 1.8 | 1.9 | V |

Notes:

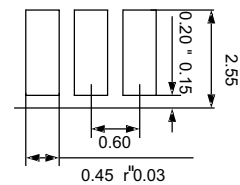
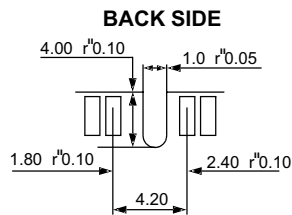
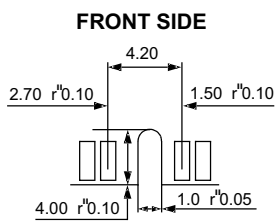
1. Under all conditions VDDQ must be less than or equal to VDD..
2. VDDQ tracks with VDD. AC parameters are measured with VDD and VDDQ tied together.

Mechanical Drawing



DETAIL a

DETAIL b



Unit: mm

Tolerances: +0.15mm unless otherwise specified

Revision History

| Revision | Date | Description | Remark |
|-----------------|-------------|------------------------------|---------------|
| 0.9 | 08/28/2012 | Official release | |
| 1.0 | 08/29/2012 | release | |
| 1.1 | 07/23/2013 | Changed headquarters address | |

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